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(12) **United States Patent**  
**Davis et al.**

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(54) **METHODS OF FABRICATING GALLIUM NITRIDE SEMICONDUCTOR LAYERS BY LATERAL OVERGROWTH**

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(\*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

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U.S. patent application Ser. No. 09/031,843, Davis et al., filed Feb. 27, 1998.

This patent is subject to a terminal disclaimer.

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(65) **Prior Publication Data**

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(57) **ABSTRACT**

**Related U.S. Application Data**

(62) Division of application No. 09/525,721, filed on Mar. 14, 2000, which is a continuation of application No. 09/032,190, filed on Feb. 27, 1998, now Pat. No. 6,051,849.

A gallium nitride semiconductor layer is fabricated by masking an underlying gallium nitride layer with a mask that includes an array of openings therein, and growing the underlying gallium nitride layer through the array of openings and onto the mask, to thereby form an overgrown gallium nitride semiconductor layer. Although dislocation defects may propagate vertically from the underlying gallium nitride layer to the grown gallium nitride layer through the mask openings, the overgrown gallium nitride layer is relatively defect free. The overgrown gallium nitride semiconductor layer may be overgrown until the overgrown gallium nitride layer coalesces on the mask, to form a continuous overgrown monocrystalline gallium nitride semiconductor layer. The gallium nitride semiconductor layer may be grown using metalorganic vapor phase epitaxy. Microelectronic devices may be formed in the overgrown gallium nitride semiconductor layer.

(51) **Int. Cl.**<sup>7</sup> ..... **H01L 21/20**; H01L 21/36

(52) **U.S. Cl.** ..... **438/481**; 438/758

(58) **Field of Search** ..... 438/46, 47, 483, 438/518, 590, 604, 605, 758, 761, 481, FOR 249, FOR 264, FOR 268, FOR 308, FOR 484

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**64 Claims, 2 Drawing Sheets**

